

Title (en)

PROCESS FOR THE MANUFACTURE OF A PALLET BLOCK

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES PALLETENBLOCKS

Title (fr)

PROCÉDÉ DE FABRICATION D'UN BLOC D'UNE PALLETTE

Publication

EP 3296073 B1 20200101 (EN)

Application

EP 17185894 A 20170811

Priority

PL 41831416 A 20160812

Abstract (en)

[origin: EP3296073A1] A pallet block comprising a particulate material glued with a binding material, said binding material being in the form of the urea-formaldehyde resin and melamine-formaldehyde resin mixture (MUF) and wherein the particulate material comprises the chipboard waste waste in amounts of from 70 do 90% by weight and the MDF and/or HDF waste in amounts of from 10 do 30% by weight, and a process for the manufacture of a pallet block which comprises the steps of (a) preparing chips from the source material, (b) charging the chips prepared in the step (a) and secondary comminution thereof, (c) drying the chips of the step (b), (d) sieving the chips prepared in the step (c), (e) buffering the chips of the step (d) and metering thereof, (f) gluing chips with the urea-formaldehyde resin and melamine-formaldehyde resin mixture (MUF), (g) compression molding of the glued chips into the form of strips, the strips being cut lengthwise to the shapes of the blocks, (e) conditioning and storage of the blocks prepared in the step (g), characterized in that for the manufacture of the chips in the step (a) the material of the chipboard waste and/or HDF and/or MDF board waste is used as a feed material, the chipboard content being from 70 to 90%, and the content of the MDF and/or HDF board waste being from 10 to 30%.

IPC 8 full level

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